

CP322-CZT3120 NPN - Power Transistor Die

3.0 Amp, 70 Volt

The CP322-CZT3120 die is a silicon power transistor designed for both power and high-speed switching applications.

B E
BACKSIDE COLLECTOR R

IONS:
66.9 x 66.9 MILS
9.05 MILS
11.8 x 17.7 MILS
11.8 x 17.7 MILS
AI - 26,000Å
Ti - 2,200Å Ni - 6,300Å Ag - 11,300Å
1.97 MILS
5 INCHES
3,620

MECHANICAL SPECIFICATIONS:

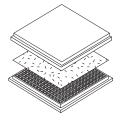
MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Collector-Base Voltage	V _{CBO}	120	V
Collector-Emitter Voltage	V _{CEO}	70	V
Emitter-Base Voltage	V _{EBO}	7.0	V
Continuous Collector Current	Ι _C	3.0	А
Operating and Storage Junction Temperature	т _Ј , т _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I _{CBO}	V _{CB} =80V			1.0	μΑ
I _{EBO}	V _{EB} =5.0V			1.0	μΑ
BVCBO	Ι _C =50μΑ	120	160		V
BVCEO	I _C =10mA	70	90		V
BVEBO	Ι _Ε =50μΑ	7.0	15		V
V _{CE(SAT)}	I _C =2.0µA, I _B =200mA		250	500	mV
V _{BE(ON)}	V _{CE} =1.0V, I _C =2.0A		0.95	1.1	V
h _{FE}	V _{CE} =5.0V, I _C =10mA	100	170		
h _{FE}	V _{CE} =5.0V, I _C =500mA	100	165	300	
h _{FE}	V _{CE} =5.0V, I _C =3.0A	40	75		
f _T	V _{CE} =10V, I _C =500mA, f=1.0MHz	8.0			MHz

BARE DIE PACKING OPTIONS



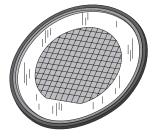


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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